



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



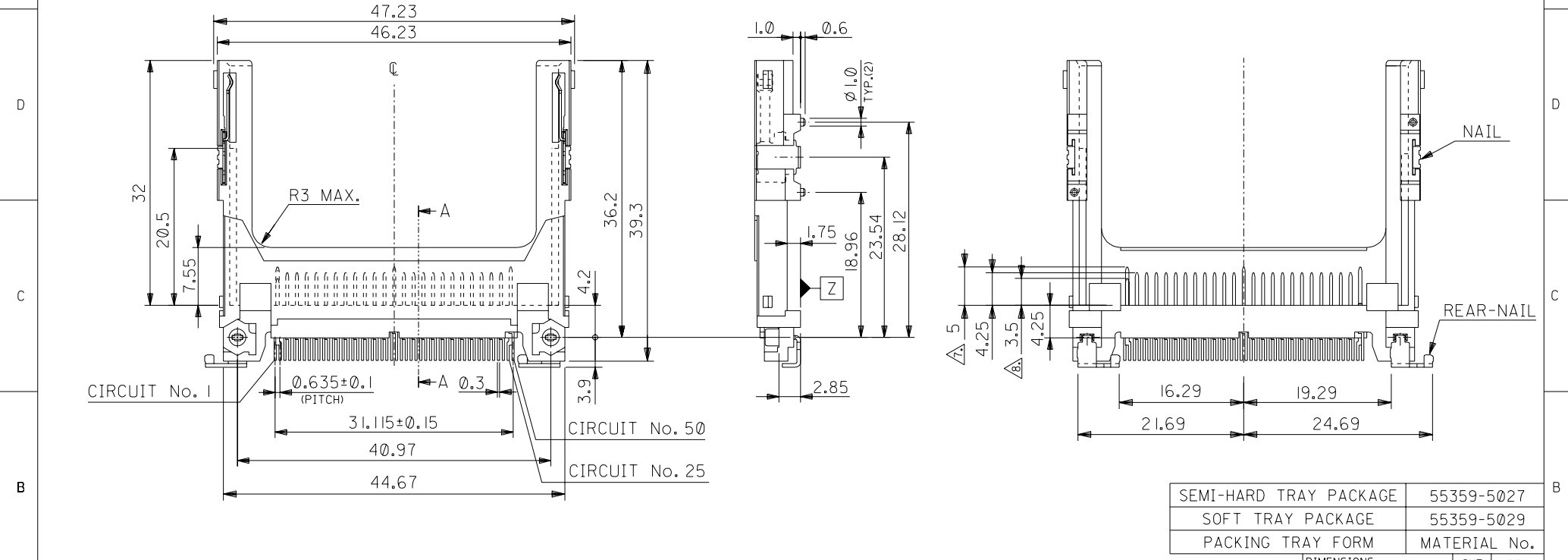
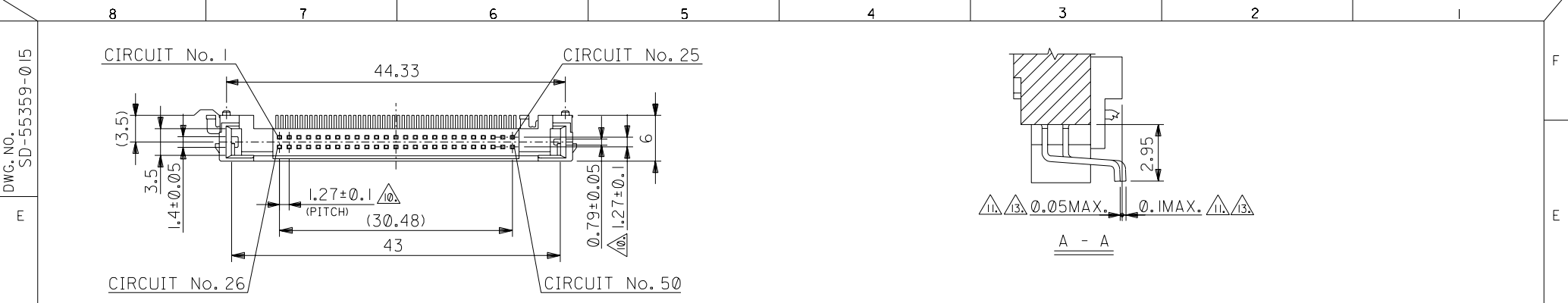
## Contact us

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SEMI-HARD TRAY PACKAGE	55359-5027
SOFT TRAY PACKAGE	55359-5029
PACKING TRAY FORM	MATERIAL NO.

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	RELEASED '04/03/22 EC NO. J2004-3249 DRWN: Y.SAKIYAMA CHK: M.SASAO APPR: M.SASAO
DO NOT SCALE DRAWING					DESCRIPTION

MATERIAL 材料	SHEET 2 OF 2 参照 REFER TO SHEET 2 OF 2	
FINISH 仕上り	SHEET 2 OF 2 参照 REFER TO SHEET 2 OF 2	
WIRE RANGE 適用線被範圍	— / —	
INS. RANGE 被覆外径	— / —	

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE	DESIGN UNITS
10 UNDER 未滿	—	<input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH
10 OVER 30 UNDER 未滿	±0.2	
30 OVER 以上	±0.25	
	±0.3	
ANGLE 角度	±3°	

DRAWN BY & DATE <i>Y. Sakiyama</i> '04/03/22	THIRD ANGLE PROJECTION	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY	SHT REV
CHECKED BY & DATE <i>H. Sasaki</i> '04/03/22			
APPROVED BY & DATE <i>M. Sasaki</i> '04/03/22	TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, REVERSE) -LEAD FREE-		
CAD FILENAME SD-55359-015.S01	MATERIAL NO. SEE CHART	DRAWING NO. SD-55359-015	SHEET NO. 1 OF 2

MOLEX INCORPORATED		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		
SIZE B		

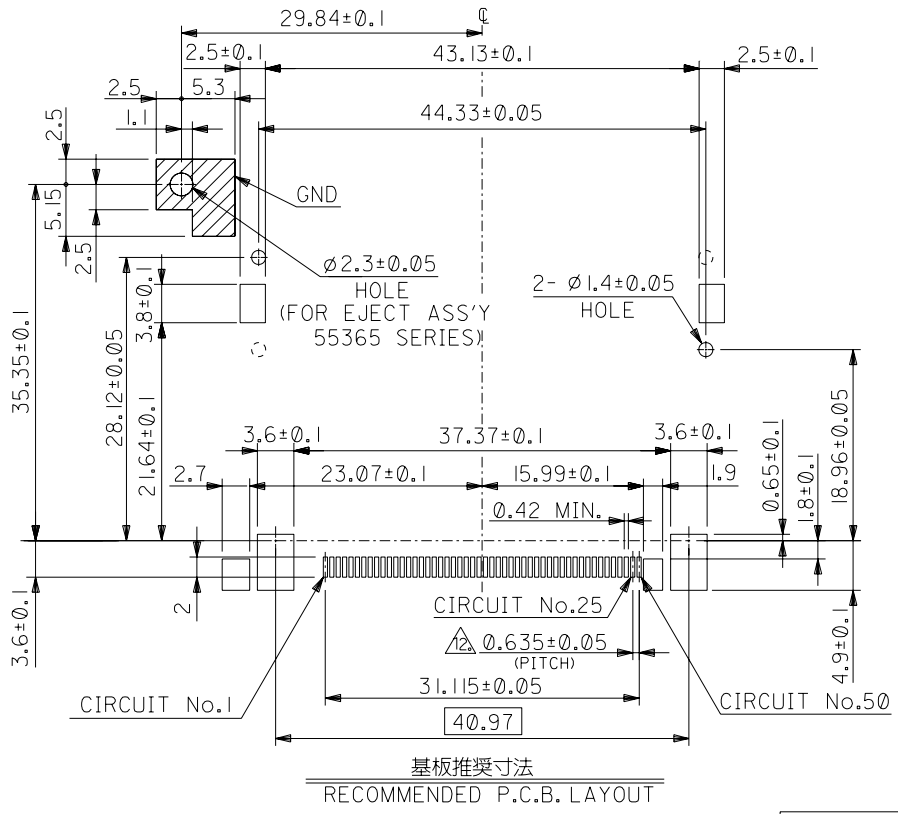
DWG. NO. SD-55359-015

- 注) 1. 材質 MATERIAL  
 ハウジング: ガラス入りLCP UL94V-0  
 HOUSING: LIQUID CRYSTAL POLYMER G.F. UL94V-0  
 ピン: リン青銅  
 PIN: PHOSPHOR BRONZE  
 ネール: リン青銅 (t0.3)  
 NAIL: PHOSPHOR BRONZE (t0.3)  
 リヤネール: リン青銅 (t0.48)  
 REAR-NAIL: PHOSPHOR BRONZE (t0.48)
2. メッキ仕様 PLATING  
 ピン 接点部: パラジウムニッケル下地、金メッキ  
 CONTACT AREA: GOLD OVER PALLADIUM-NICKEL PLATING  
 半田付け部: 錫メッキ  
 SOLDER TAIL AREA: TIN PLATING  
 下地メッキ: ニッケルメッキ  
 UNDER PLATING: NICKEL ALL OVER PLATING
- ネール 接点部: 金メッキ  
 CONTACT AREA: GOLD PLATING  
 半田付け部: 錫メッキ  
 SOLDER TAIL AREA: TIN PLATING  
 下地メッキ: ニッケルメッキ  
 UNDER PLATING: NICKEL ALL OVER PLATING
- リヤネール 錫メッキ  
 REAR-NAIL TIN PLATING  
 下地メッキ: ニッケルメッキ  
 UNDER PLATING: NICKEL ALL OVER PLATING
3. 推奨基板厚: t=0.8 MIN.  
 RECOMMENDED P.C.B. THICKNESS: t=0.8 MIN.
4. 適合カード厚  
 RECOMMENDED CARD THICKNESS  
 接続部: 3.3±0.1  
 CONNECTING AREA: 3.3±0.1
5. 適合カード幅: 42.8±0.1  
 RECOMMENDED CARD WIDTH: 42.8±0.1
6. ハウジング色: 黒  
 HOUSING COLOR: BLACK
- △1. 寸法適用極: 1,13,38,50  
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 1,13,38 AND 50.
- △2. 寸法適用極: 25,26  
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.
- △3. ピンの倒れは、ピン根元を基準に全方向へ0.1 MAX.とする。  
 PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1 WHEN MEASURED FROM PIN BASE.
- △4. ピン根元に適用する。  
 THIS DIMENSION TO BE MEASURED AT PIN BASE.

- △1. ソルダータールは、Z面を基準とし上へ0.05下へ0.1の範囲にあり、且つソルダータールの平坦度は、0.1 MAX.とし、テール先端にて測定する。  
 SOLDER TAILS TO BE WITHIN 0.05 UPWARD AND 0.1 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY OF SOLDER TAILS TO BE WITHIN 0.1. MEASUREMENT POINT IS SOLDER TAILS TIP.
- △2. 公差非累積  
 NON-CUMULATIVE
- △3. テールとネール、リヤネールを併せた平坦度は、0.1 MAX.とする。  
 TOTAL COPLANARITY OF SOLDER TAILS, NAILS AND REAR-NAILS TO BE 0.1 MAX.

14. 鉛フリー対応表  
 CORRESPONDENCE TABLE OF LEAD FREE

	SEMI-HARD TRAY PKG	SOFT TRAY PKG
半田品 LEAD CONTENT	55359 -5026	55359 -5021
鉛フリー品 LEAD FREE	55359 -5027	55359 -5029



DO NOT SCALE DRAWING

EC NO. DRAWN: CH'K: APPR:		EC NO. DRAWN: CH'K: APPR:		EC NO. DRAWN: CH'K: APPR:		EC NO. DRAWN: CH'K: APPR:		EC NO. DRAWN: CH'K: APPR:		RELEASED '04/03/22 EC NO. J2004-3249 DRWN: Y.SAKIYAMA CH'K: M.SASAO APPR: M.SASAO		MATERIAL 材料 注記参照 SEE NOTES		GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE 1:1 DESIGN UNITS mm INCH		THIRD ANGLE PROJECTION		DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY		SHT REV REVISE ON CAD ONLY	
										WIRE RANGE 適用電線範囲 〃 〃		FINISH 仕上げ 注記参照 SEE NOTES		10 UNDER 未満 ±0.2 DRAWN BY & DATE Y.Sakiyama '04/03/22		10 OVER 30 UNDER 未満 ±0.25 CHECKED BY & DATE H. Sasaki '04/03/22		30 OVER 以上 ±0.3 APPROVED BY & DATE H. Sasaki '04/03/22		TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, REVERSE) -LEAD FREE-		MOLEX MOLEX INCORPORATED	
										WIRE RANGE 適用電線範囲 〃 〃		ANGLE 角度 ±3°		CAD FILENAME SD-55359-015.S02		MATERIAL NO. SEE CHART		DRAWING NO. SD-55359-015		SHEET NO. 2 OF 2			
												THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.										SIZE B	